

# IS62/65WV2568DALL IS62/65WV2568DBLL



## 256K x 8 LOW VOLTAGE, ULTRA LOW POWER CMOS STATIC RAM

JULY 2017

### FEATURES

- High-speed access time: 35ns, 45ns, 55ns
- CMOS low power operation
  - 36 mW (typical) operating
  - 9  $\mu$ W (typical) CMOS standby
- TTL compatible interface levels
- Single power supply
  - 1.8V  $\pm$  10% V<sub>CC</sub> (IS62/65WV2568DALL)
  - 2.5V–3.6V V<sub>CC</sub> (IS62/65WV2568DBLL)
- Fully static operation: no clock or refresh required
- Three state outputs
- Industrial temperature available
- Lead-free available

### DESCRIPTION

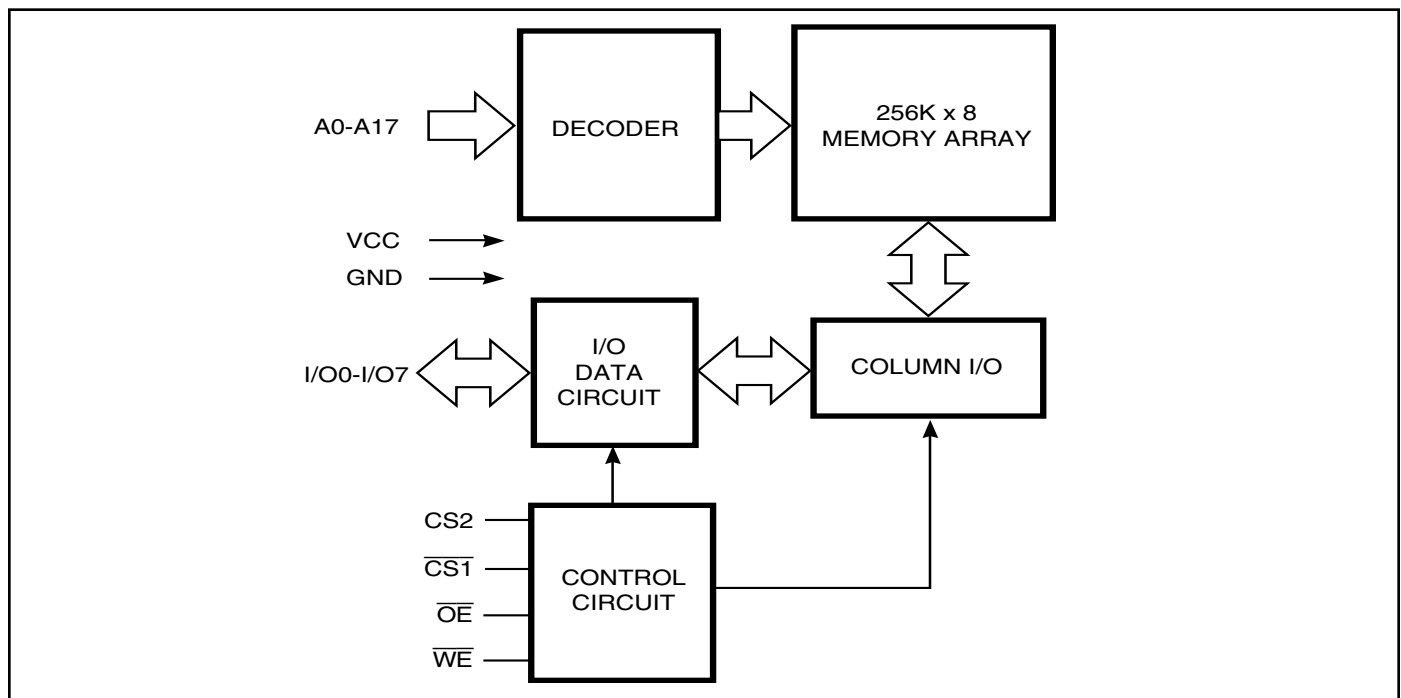
The *ISSI* IS62/65WV2568DALL and IS62/65WV2568DBLL are high-speed, 2M bit static RAMs organized as 256K words by 8 bits. It is fabricated using *ISSI*'s high-performance CMOS technology. This highly reliable process coupled with innovative circuit design techniques, yields high-performance and low power consumption devices.

When  $\overline{\text{CS1}}$  is HIGH (deselected) or when CS2 is LOW (deselected), the device assumes a standby mode at which the power dissipation can be reduced down with CMOS input levels.

Easy memory expansion is provided by using Chip Enable and Output Enable inputs. The active LOW Write Enable ( $\overline{\text{WE}}$ ) controls both writing and reading of the memory.

The IS62/65WV2568DALL and IS62/65WV2568DBLL are packaged in the JEDEC standard 32-pin TSOP (TYPE I), sTSOP (TYPE I), and 36-pin mini BGA.

### FUNCTIONAL BLOCK DIAGRAM



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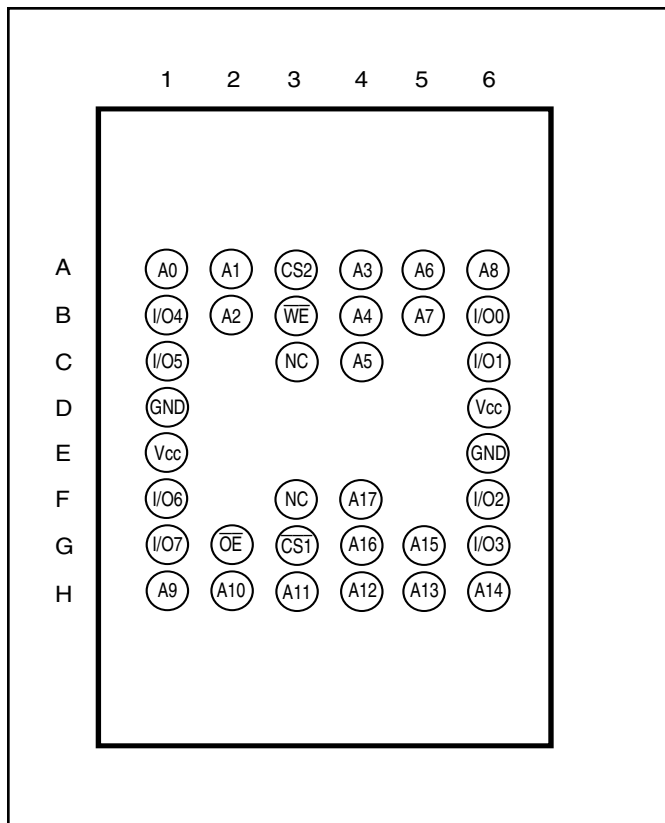
- a.) the risk of injury or damage has been minimized;
- b.) the user assume all such risks; and
- c.) potential liability of Integrated Silicon Solution, Inc is adequately protected under the circumstances

**PIN DESCRIPTIONS**

|                  |                     |
|------------------|---------------------|
| A0-A17           | Address Inputs      |
| $\overline{CS1}$ | Chip Enable 1 Input |
| CS2              | Chip Enable 2 Input |
| $\overline{OE}$  | Output Enable Input |
| $\overline{WE}$  | Write Enable Input  |
| I/O0-I/O7        | Input/Output        |
| NC               | No Connection       |
| Vcc              | Power               |
| GND              | Ground              |

**PIN CONFIGURATION**

**36-pin mini BGA (B) (6mm x 8mm)**



**32-pin TSOP (TYPE I), sTSOP (TYPE I)**



**ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>**

| Symbol            | Parameter                            | Value                        | Unit |
|-------------------|--------------------------------------|------------------------------|------|
| V <sub>TERM</sub> | Terminal Voltage with Respect to GND | -0.2 to V <sub>CC</sub> +0.3 | V    |
| T <sub>STG</sub>  | Storage Temperature                  | -65 to +150                  | °C   |
| P <sub>T</sub>    | Power Dissipation                    | 1.0                          | W    |

**Note:**

1. Stress greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

**OPERATING RANGE (V<sub>CC</sub>)**

| Range           | Ambient Temperature | IS62/65WV2568DALL | IS62/65WV2568DBLL |
|-----------------|---------------------|-------------------|-------------------|
| Commercial      | 0°C to +70°C        | 1.8V ± 10%        | 2.5V - 3.6V       |
| Industrial      | -40°C to +85°C      | 1.8V ± 10%        | 2.5V - 3.6V       |
| Automotive (A3) | -40°C to +125°C     | 1.8V ± 10%        | 2.5V - 3.6V       |

**DC ELECTRICAL CHARACTERISTICS (Over Operating Range)**

| Symbol                         | Parameter           | Test Conditions   | V <sub>CC</sub> | Min. | Max.                  | Unit |
|--------------------------------|---------------------|---|-----------------|------|-----------------------|------|
| V <sub>OH</sub>                | Output HIGH Voltage | I <sub>OH</sub> = -0.1 mA<br>I <sub>OH</sub> = -1 mA        | 1.8V ± 10%      | 1.4  | —                     | V    |
|                                |                     |   | 2.5-3.6V        | 2.2  | —                     | V    |
| V <sub>OL</sub>                | Output LOW Voltage  | I <sub>OL</sub> = 0.1 mA<br>I <sub>OL</sub> = 1.0 mA        | 1.8V ± 10%      | —    | 0.2                   | V    |
|                                |                     |   | 2.5-3.6V        | —    | 0.4                   | V    |
| V <sub>IH</sub>                | Input HIGH Voltage  |   | 1.8V ± 10%      | 1.4  | V <sub>CC</sub> + 0.2 | V    |
|                                |                     |   | 2.5-3.6V        | 2.2  | V <sub>CC</sub> + 0.3 | V    |
| V <sub>IL</sub> <sup>(1)</sup> | Input LOW Voltage   |   | 1.8V ± 10%      | -0.2 | 0.4                   | V    |
|                                |                     |   | 2.5-3.6V        | -0.2 | 0.6                   | V    |
| I <sub>LI</sub>                | Input Leakage       | GND ≤ V <sub>IN</sub> ≤ V <sub>CC</sub>                     |                 | -1   | 1                     | μA   |
| I <sub>LO</sub>                | Output Leakage      | GND ≤ V <sub>OUT</sub> ≤ V <sub>CC</sub> , Outputs Disabled |                 | -1   | 1                     | μA   |

**Notes:**

For IS62/65WV2568DALL:

V<sub>IL</sub> (min.) = -1.0V AC (pulse width < 10ns). Not 100% tested.

V<sub>IH</sub> (max.) = V<sub>CC</sub> + 1.0V AC; (pulse width < 10ns). Not 100% tested.

For IS62/65WV2568DBLL:

V<sub>IL</sub> (min.) = -2.0V AC (pulse width < 10ns). Not 100% tested.

V<sub>IH</sub> (max.) = V<sub>CC</sub> + 2.0V AC; (pulse width < 10ns). Not 100% tested.

**CAPACITANCE<sup>(1)</sup>**

| Symbol           | Parameter                | Conditions            | Max. | Unit |
|------------------|--------------------------|-----------------------|------|------|
| C <sub>IN</sub>  | Input Capacitance        | V <sub>IN</sub> = 0V  | 8    | pF   |
| C <sub>OUT</sub> | Input/Output Capacitance | V <sub>OUT</sub> = 0V | 10   | pF   |

**Note:**

1. Tested initially and after any design or process changes that may affect these parameters.

**AC TEST CONDITIONS**

| Parameter                                   | 62WV2568DALL<br>(Unit)        | 62WV2568DBLL<br>(Unit)        |
|---|-------------------------------|-------------------------------|
| Input Pulse Level                           | 0.4V to V <sub>CC</sub> -0.2V | 0.4V to V <sub>CC</sub> -0.3V |
| Input Rise and Fall Times                   | 5 ns                          | 5ns                           |
| Input and Output Timing and Reference Level | V <sub>REF</sub>              | V <sub>REF</sub>              |
| Output Load                                 | See Figures 1 and 2           | See Figures 1 and 2           |

|                  | 1.8V ± 10% | 2.5V - 3.6V |
|------------------|------------|-------------|
| R1(Ω)            | 3070       | 3070        |
| R2(Ω)            | 3150       | 3150        |
| V <sub>REF</sub> | 0.9V       | 1.5V        |
| V <sub>TM</sub>  | 1.8V       | 2.8V        |

**AC TEST LOADS**

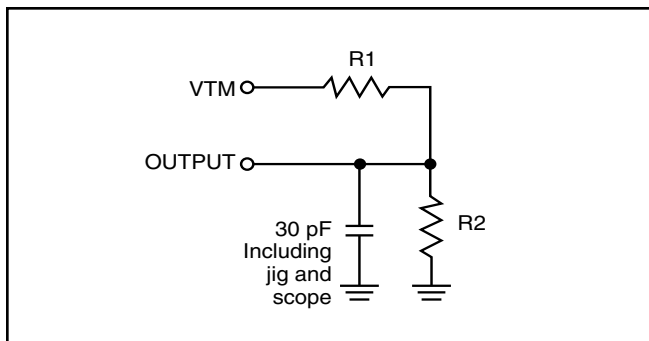


Figure 1

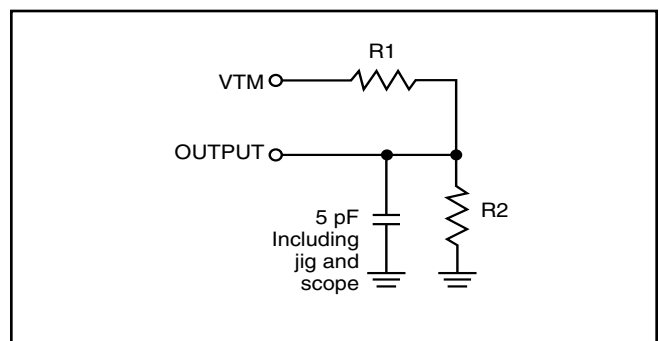


Figure 2

**POWER SUPPLY CHARACTERISTICS<sup>(1)</sup>** (Over Operating Range)

| Symbol           | Parameter  | Test Conditions  |                     | Max. | Max. | Max. | Unit |
|------------------|--|--|---------------------|------|------|------|------|
|                  |  |  |                     | 35ns | 45ns | 55ns |      |
| I <sub>CC</sub>  | V <sub>CC</sub> Dynamic Operating Supply Current | V <sub>CC</sub> = Max.,<br>I <sub>OUT</sub> = 0 mA, f = f <sub>MAX</sub>   | Com.                | 15   | 12   | 10   | mA   |
|                  |  |  | Ind.                | 20   | 15   | 12   |      |
|                  |  |  | Auto.               | 25   | 20   | 15   |      |
|                  |  |  | typ. <sup>(2)</sup> | 10   | 8    | 6    |      |
| I <sub>SB1</sub> | TTL Standby Current (TTL Inputs)                 | CS <sub>2</sub> = V <sub>IL</sub><br>f = 0Hz   | Com.                | 0.1  | 0.1  | 0.1  | mA   |
|                  |  |  | Ind.                | 0.2  | 0.2  | 0.2  |      |
|                  |  |  | Auto.               | 0.3  | 0.3  | 0.3  |      |
| I <sub>SB2</sub> | CMOS Standby Current (CMOS Inputs)               | (1) 0V ≤ CS <sub>2</sub> ≤ 0.2V<br>OR<br>(2) $\overline{CS1} \geq VDD - 0.2V$ ,<br>CS <sub>2</sub> ≥ VDD - 0.2V<br>f = 0Hz | Com.                | 7    | 7    | 7    | μA   |
|                  |  |  | Ind.                | 10   | 10   | 10   |      |
|                  |  |  | Auto.               | –    | 30   | 30   |      |
|                  |  |  | typ. <sup>(2)</sup> |      | 3    |      |      |

**Note:**

- At f = f<sub>MAX</sub>, address and data inputs are cycling at the maximum frequency, f = 0 means no input lines change.
- Typical values are measured at V<sub>CC</sub> = 3.0V, T<sub>a</sub> = 25°C and not 100% tested.



# IS62/65WV2568DALL, IS62/65WV2568DBLL

## READ CYCLE SWITCHING CHARACTERISTICS<sup>(1)</sup> (Over Operating Range)

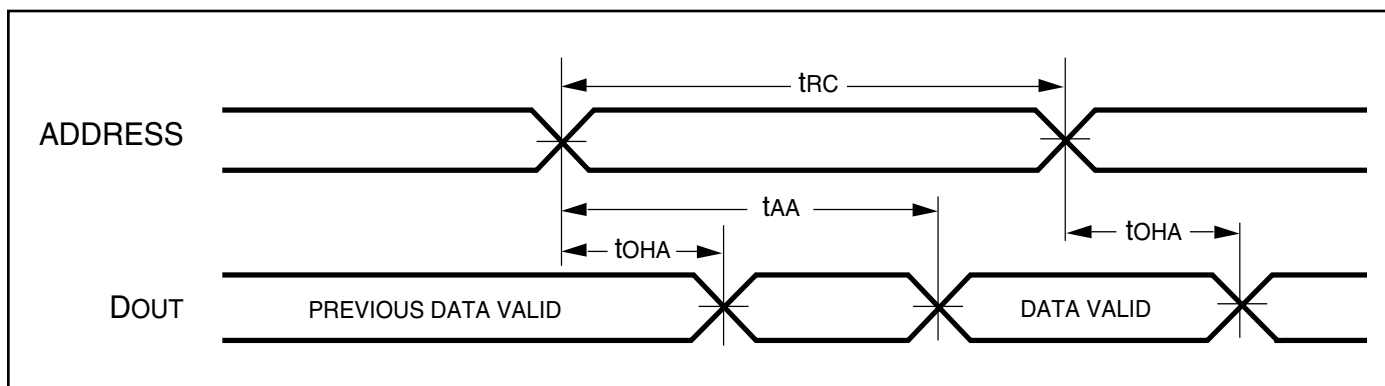
| Symbol  | Parameter                              | 35ns |      | 45ns |      | 55ns |      | Unit |
|---|--|------|------|------|------|------|------|------|
|   |  | Min. | Max. | Min. | Max. | Min. | Max. |      |
| t <sub>RC</sub>                                       | Read Cycle Time                        | 35   | —    | 45   | —    | 55   | —    | ns   |
| t <sub>AA</sub>                                       | Address Access Time                    | —    | 35   | —    | 45   | —    | 55   | ns   |
| t <sub>OHA</sub>                                      | Output Hold Time                       | 10   | —    | 10   | —    | 10   | —    | ns   |
| t <sub>ACS1</sub> /t <sub>ACS2</sub>                  | $\overline{CS1}$ /CS2 Access Time      | —    | 35   | —    | 45   | —    | 55   | ns   |
| t <sub>DOE</sub>                                      | $\overline{OE}$ Access Time            | —    | 15   | —    | 20   | —    | 25   | ns   |
| t <sub>HZOE</sub> <sup>(2)</sup>                      | $\overline{OE}$ to High-Z Output       | —    | 10   | —    | 15   | —    | 20   | ns   |
| t <sub>LZOE</sub> <sup>(2)</sup>                      | $\overline{OE}$ to Low-Z Output        | 5    | —    | 5    | —    | 5    | —    | ns   |
| t <sub>HZCS1</sub> /t <sub>HZCS2</sub> <sup>(2)</sup> | $\overline{CS1}$ /CS2 to High-Z Output | 0    | 10   | 0    | 15   | 0    | 20   | ns   |
| t <sub>LZCS1</sub> /t <sub>LZCS2</sub> <sup>(2)</sup> | $\overline{CS1}$ /CS2 to Low-Z Output  | 10   | —    | 10   | —    | 10   | —    | ns   |

### Notes:

1. Test conditions and output loading conditions are specified in the AC Test Conditions and AC Test Loads (Figure 1).
2. Tested with the load in Figure 2. Transition is measured  $\pm 500$  mV from steady-state voltage. Not 100% tested.

## AC WAVEFORMS

### READ CYCLE NO. 1<sup>(1,2)</sup> (Address Controlled) ( $\overline{CS1} = \overline{OE} = V_{IL}$ , $CS2 = \overline{WE} = V_{IH}$ )



**AC WAVEFORMS**

**READ CYCLE NO. 2<sup>(1,3)</sup> ( $\overline{CS1}$ ,  $CS2$ ,  $\overline{OE}$  Controlled)**



**Notes:**

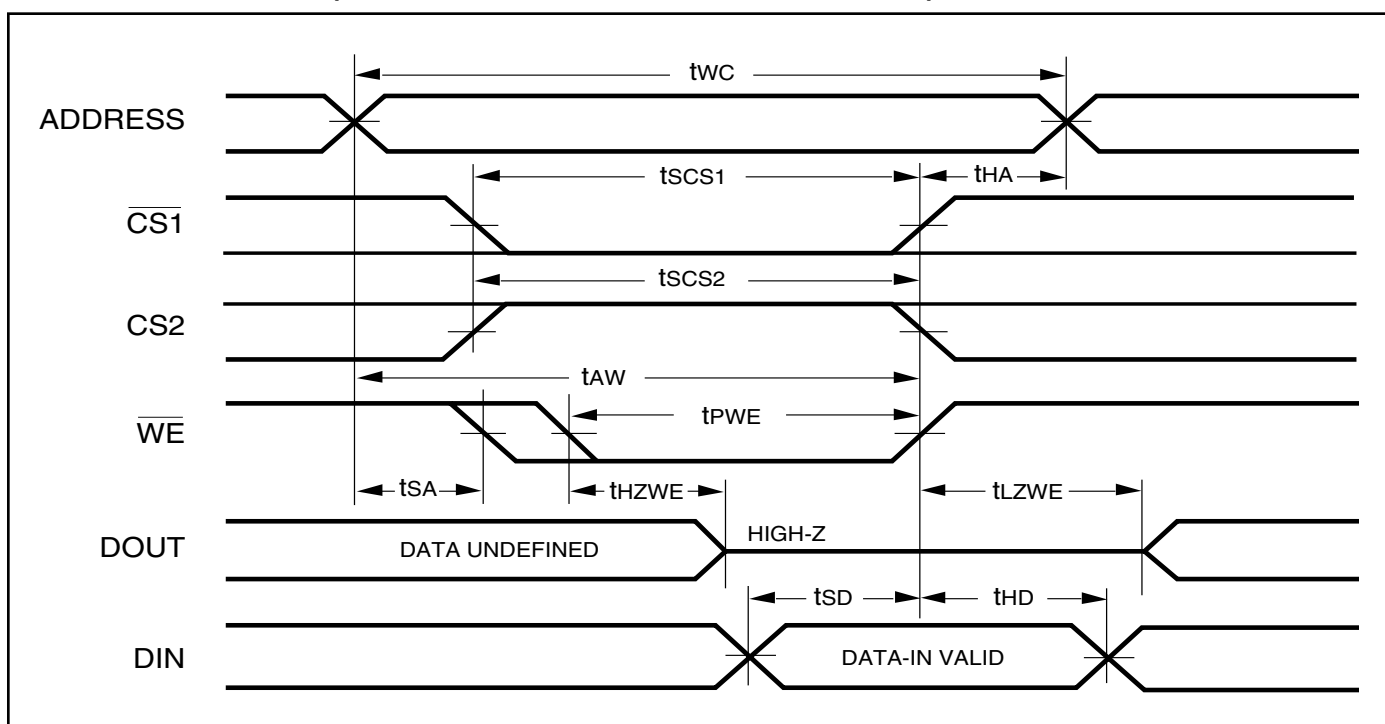
1.  $\overline{WE}$  is HIGH for a Read Cycle.
2. The device is continuously selected.  $\overline{OE}$ ,  $\overline{CS1} = V_{IL}$ .  $CS2 = \overline{WE} = V_{IH}$ .
3. Address is valid prior to or coincident with  $\overline{CS1}$  LOW and  $CS2$  HIGH transition.

**WRITE CYCLE SWITCHING CHARACTERISTICS<sup>(1,2)</sup>** (Over Operating Range)

| Symbol                               | Parameter                            | 35ns |      | 45ns |      | 55ns |      | Unit |
|--------------------------------------|--------------------------------------|------|------|------|------|------|------|------|
|                                      |                                      | Min. | Max. | Min. | Max. | Min. | Max. |      |
| t <sub>WC</sub>                      | Write Cycle Time                     | 35   | —    | 45   | —    | 55   | —    | ns   |
| t <sub>scs1</sub> /t <sub>scs2</sub> | $\overline{CS1}/CS2$ to Write End    | 25   | —    | 35   | —    | 45   | —    | ns   |
| t <sub>AW</sub>                      | Address Setup Time to Write End      | 25   | —    | 35   | —    | 45   | —    | ns   |
| t <sub>HA</sub>                      | Address Hold from Write End          | 0    | —    | 0    | —    | 0    | —    | ns   |
| t <sub>SA</sub>                      | Address Setup Time                   | 0    | —    | 0    | —    | 0    | —    | ns   |
| t <sub>PWE</sub>                     | $\overline{WE}$ Pulse Width          | 30   | —    | 35   | —    | 40   | —    | ns   |
| t <sub>SD</sub>                      | Data Setup to Write End              | 15   | —    | 20   | —    | 25   | —    | ns   |
| t <sub>HD</sub>                      | Data Hold from Write End             | 0    | —    | 0    | —    | 0    | —    | ns   |
| t <sub>HZWE</sub>                    | $\overline{WE}$ LOW to High-Z Output | —    | 20   | —    | 20   | —    | 20   | ns   |
| t <sub>LZWE</sub>                    | $\overline{WE}$ HIGH to Low-Z Output | 5    | —    | 5    | —    | 5    | —    | ns   |

**Notes:**

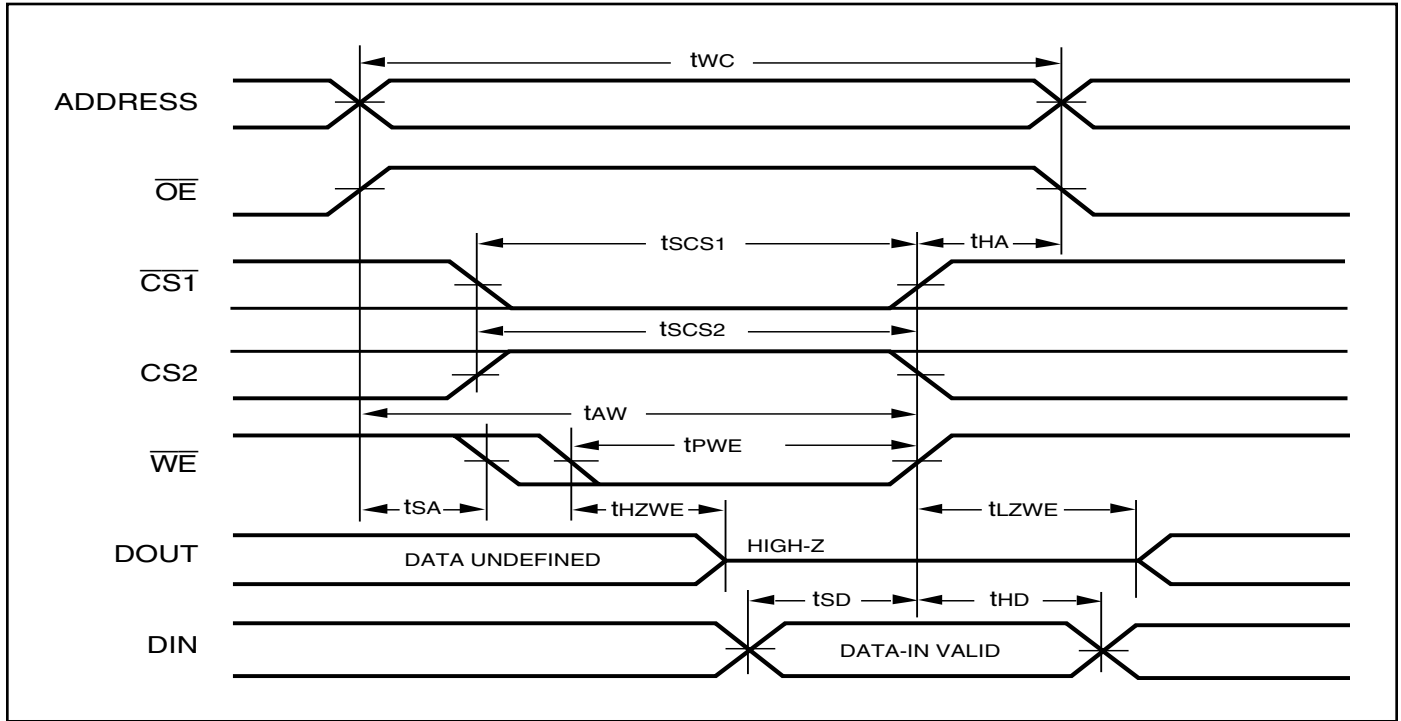
1. Test conditions and output loading conditions are specified in the AC Test Conditions and AC Test Loads (Figure 1).
2. The internal write time is defined by the overlap of  $\overline{CS1}$  LOW, CS2 HIGH and  $\overline{WE}$  LOW. All signals must be in valid states to initiate a Write, but any one can go inactive to terminate the Write. The Data Input Setup and Hold timing are referenced to the rising or falling edge of the signal that terminates the write.
3. Tested with the load in Figure 2. Transition is measured  $\pm 500$  mV from steady-state voltage. Not 100% tested.

**AC WAVEFORMS****WRITE CYCLE NO. 1** ( $\overline{CS1}/CS2$  Controlled,  $\overline{OE} = \text{HIGH or LOW}$ )

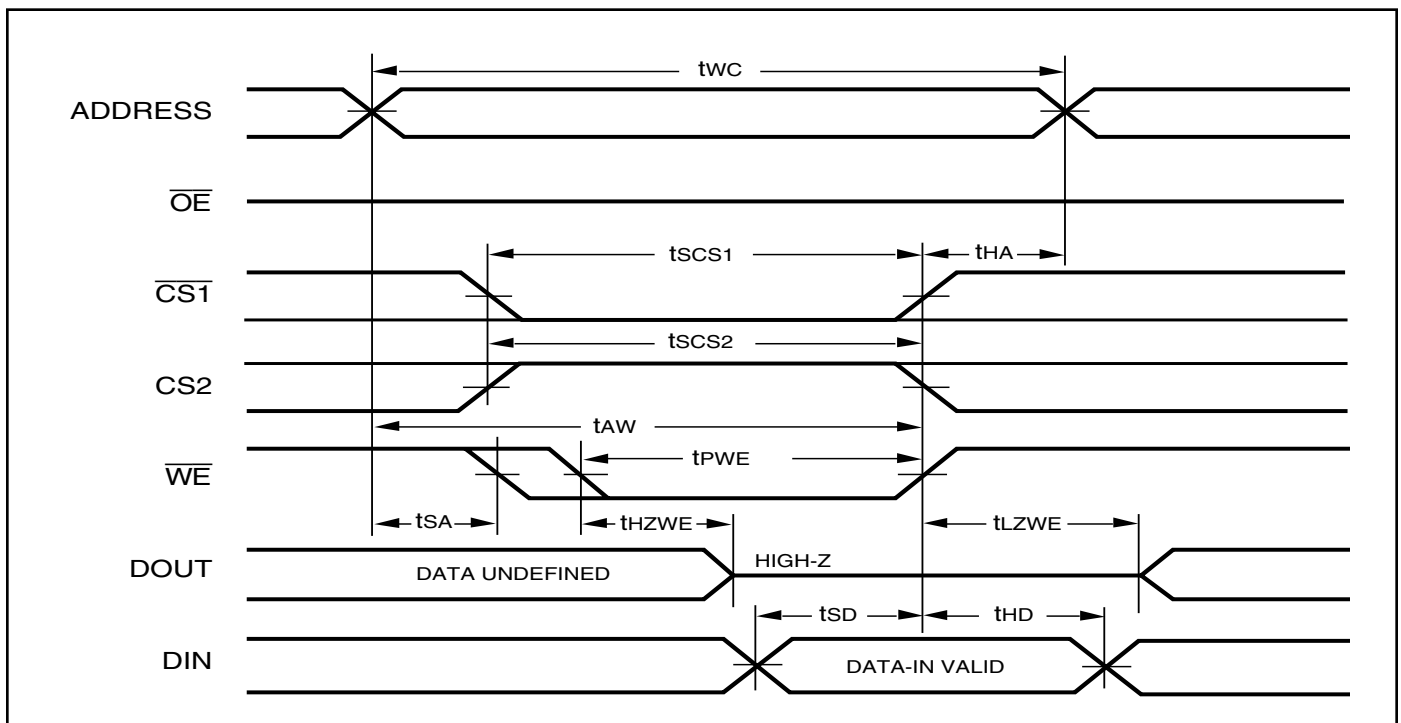


**AC WAVEFORMS**

**WRITE CYCLE NO. 2** ( $\overline{WE}$  Controlled:  $\overline{OE}$  is HIGH During Write Cycle)



**WRITE CYCLE NO. 3** ( $\overline{WE}$  Controlled:  $\overline{OE}$  is LOW During Write Cycle)



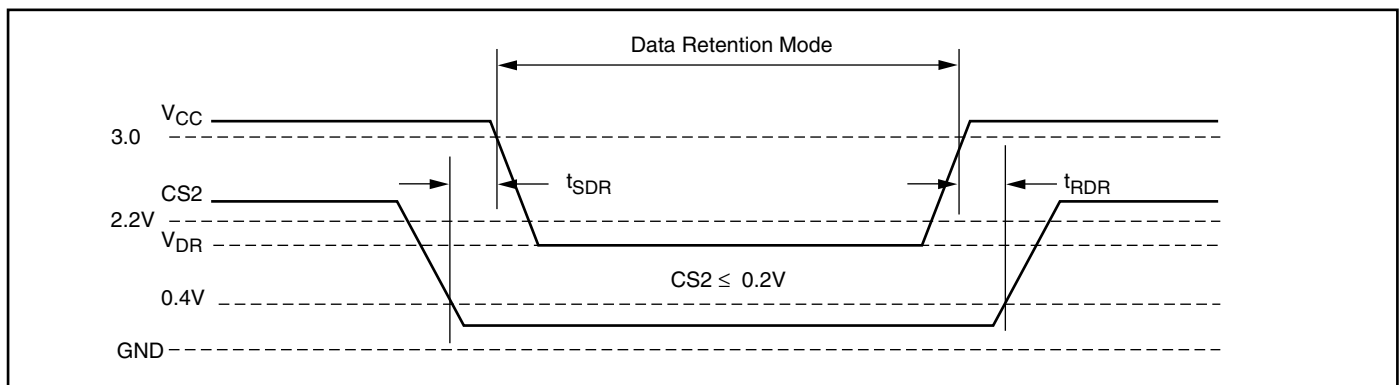
**DATA RETENTION SWITCHING CHARACTERISTICS**

| Symbol           | Parameter                          | Test Condition  | Min.                                      | Max.               | Unit |
|------------------|------------------------------------|---|---|--------------------|------|
| V <sub>DR</sub>  | V <sub>CC</sub> for Data Retention | See Data Retention Waveform   | 1.5                                       | 3.6                | V    |
| I <sub>DR</sub>  | Data Retention Current             | (1) 0V ≤ CS2 ≤ 0.2V, or<br>(2) CS1 ≥ V <sub>DD</sub> - 0.2V, CS2 ≥ V <sub>DD</sub> - 0.2V | Com.<br>—<br>Auto.<br>typ. <sup>(1)</sup> | 7<br>10<br>20<br>2 | μA   |
| t <sub>SDR</sub> | Data Retention Setup Time          | See Data Retention Waveform   | 0   | —                  | ns   |
| t <sub>RDR</sub> | Recovery Time                      | See Data Retention Waveform   | t <sub>RC</sub>                           | —                  | ns   |

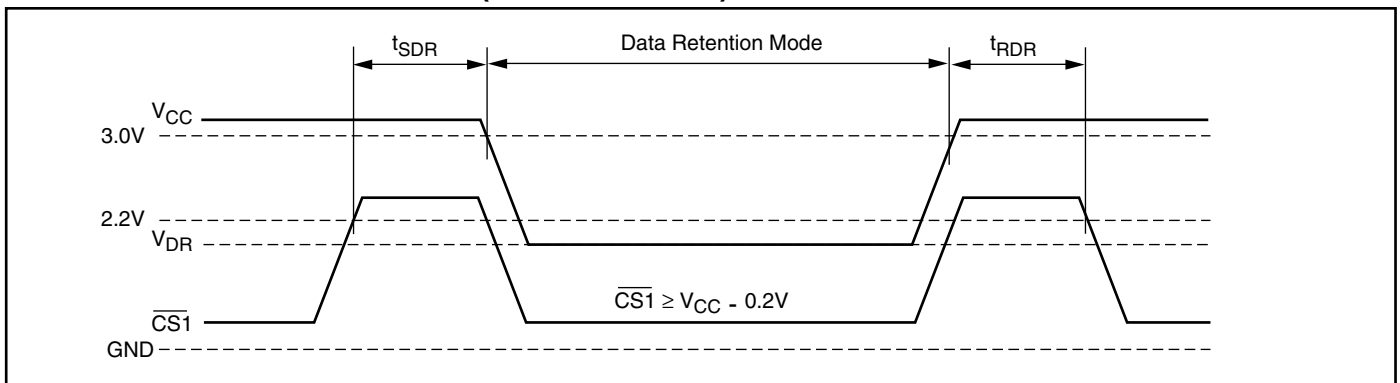
**Note:**

1. Typical values are measured at V<sub>CC</sub> = V<sub>DR</sub>(min), T<sub>A</sub> = 25°C and not 100% tested.

**DATA RETENTION WAVEFORM (CS2 Controlled)**



**DATA RETENTION WAVEFORM ( $\overline{CS1}$  Controlled)**



**Note:** CS2 must satisfy either CS2 ≥ V<sub>CC</sub> - 0.2V or CS2 ≤ 0.2V

**ORDERING INFORMATION**
**IS62WV2568DALL (1.8 ± 10%)**
**Industrial Range: -40°C to +85°C**

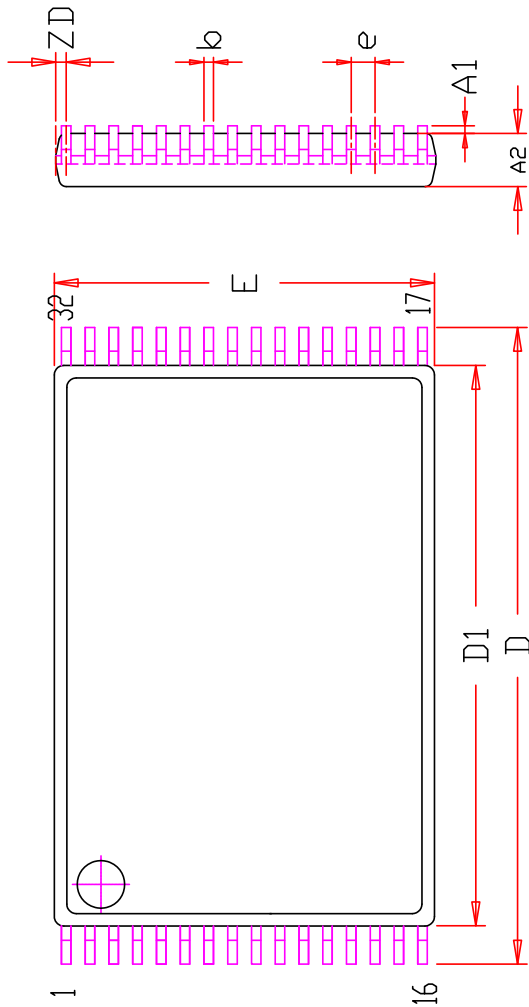
| Speed (ns) | Order Part No.       | Package                         |
|------------|----------------------|---------------------------------|
| 55         | IS62WV2568DALL-55TI  | TSOP, TYPE I                    |
| 55         | IS62WV2568DALL-55TLI | TSOP, TYPE I, Lead-free         |
| 55         | IS62WV2568DALL-55BI  | mini BGA (6mm x 8mm)            |
| 55         | IS62WV2568DALL-55BLI | mini BGA (6mm x 8mm), Lead-free |
| 55         | IS62WV2568DALL-55HI  | sTSOP, TYPE I                   |
| 55         | IS62WV2568DALL-55HLI | sTSOP, TYPE I, Lead-free        |

**IS62WV2568DBLL (2.5V - 3.6V)**
**Industrial Range: -40°C to +85°C**

| Speed (ns) | Order Part No.       | Package                         |
|------------|----------------------|---------------------------------|
| 35         | IS62WV2568DBLL-35HLI | sTSOP, TYPE I                   |
| 35         | IS62WV2568DBLL-35TLI | TSOP, TYPE I, Lead-free         |
| 45         | IS62WV2568DBLL-45TI  | TSOP, TYPE I                    |
| 45         | IS62WV2568DBLL-45TLI | TSOP, TYPE I, Lead-free         |
| 45         | IS62WV2568DBLL-45BI  | mini BGA (6mm x 8mm)            |
| 45         | IS62WV2568DBLL-45BLI | mini BGA (6mm x 8mm), Lead-free |
| 45         | IS62WV2568DBLL-45HI  | sTSOP, TYPE I                   |
| 45         | IS62WV2568DBLL-45HLI | sTSOP, TYPE I, Lead-free        |

**IS65WV2568DBLL (2.5V - 3.6V)**
**Automotive Range (A3): -40°C to +125°C**

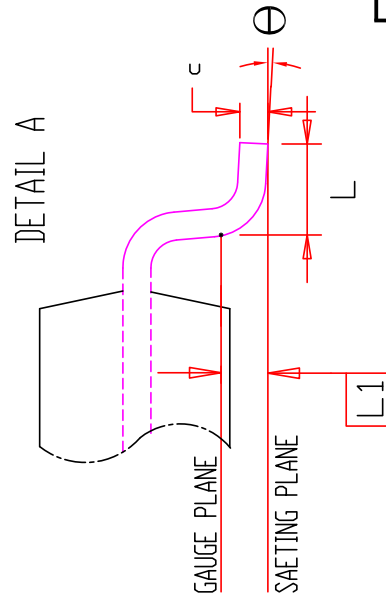
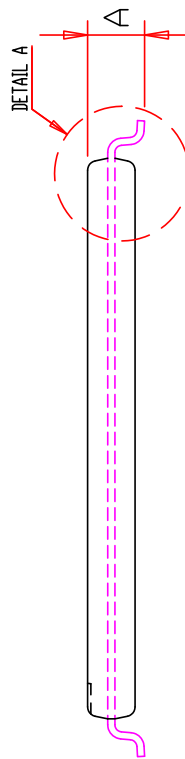
| Speed (ns) | Order Part No.        | Package                  |
|------------|-----------------------|--------------------------|
| 45         | IS65WV2568DBLL-45TLA3 | TSOP, TYPE I, Lead-free  |
| 45         | IS65WV2568DBLL-45HLA3 | sTSOP, TYPE I, Lead-free |



| SYMBOL    | DIMENSION IN MM |           |       | DIMENSION IN INCH |            |       |
|-----------|-----------------|-----------|-------|-------------------|------------|-------|
|           | MIN             | NOM       | MAX   | MIN               | NOM        | MAX   |
| A         | 0.95            |           | 1.25  | 0.037             |            | 0.049 |
| A1        | 0.05            |           | 0.15  | 0.002             |            | 0.008 |
| A2        | 0.90            |           | 1.05  | 0.035             |            | 0.041 |
| b         | 0.16            |           | 0.27  | 0.006             |            | 0.011 |
| D         | 13.10           | 13.40     | 13.70 | 0.516             | 0.528      | 0.539 |
| D1        | 11.70           | 11.80     | 11.90 | 0.461             | 0.465      | 0.469 |
| E         | 7.90            | 8.00      | 8.10  | 0.311             | 0.315      | 0.319 |
| e         |                 | 0.50 BSC. |       |                   | 0.020 BSC. |       |
| L         | 0.30            | 0.50      | 0.70  | 0.012             | 0.020      | 0.028 |
| L1        |                 | 0.25 BSC. |       |                   | 0.010 BSC. |       |
| ZD        |                 | 0.25 REF. |       |                   | 0.010 REF. |       |
| $\ominus$ | 0               | 3°        | 5°    | 0                 | 3°         | 5°    |
| c         | 0.10            |           | 0.21  | 0.004             |            | 0.008 |

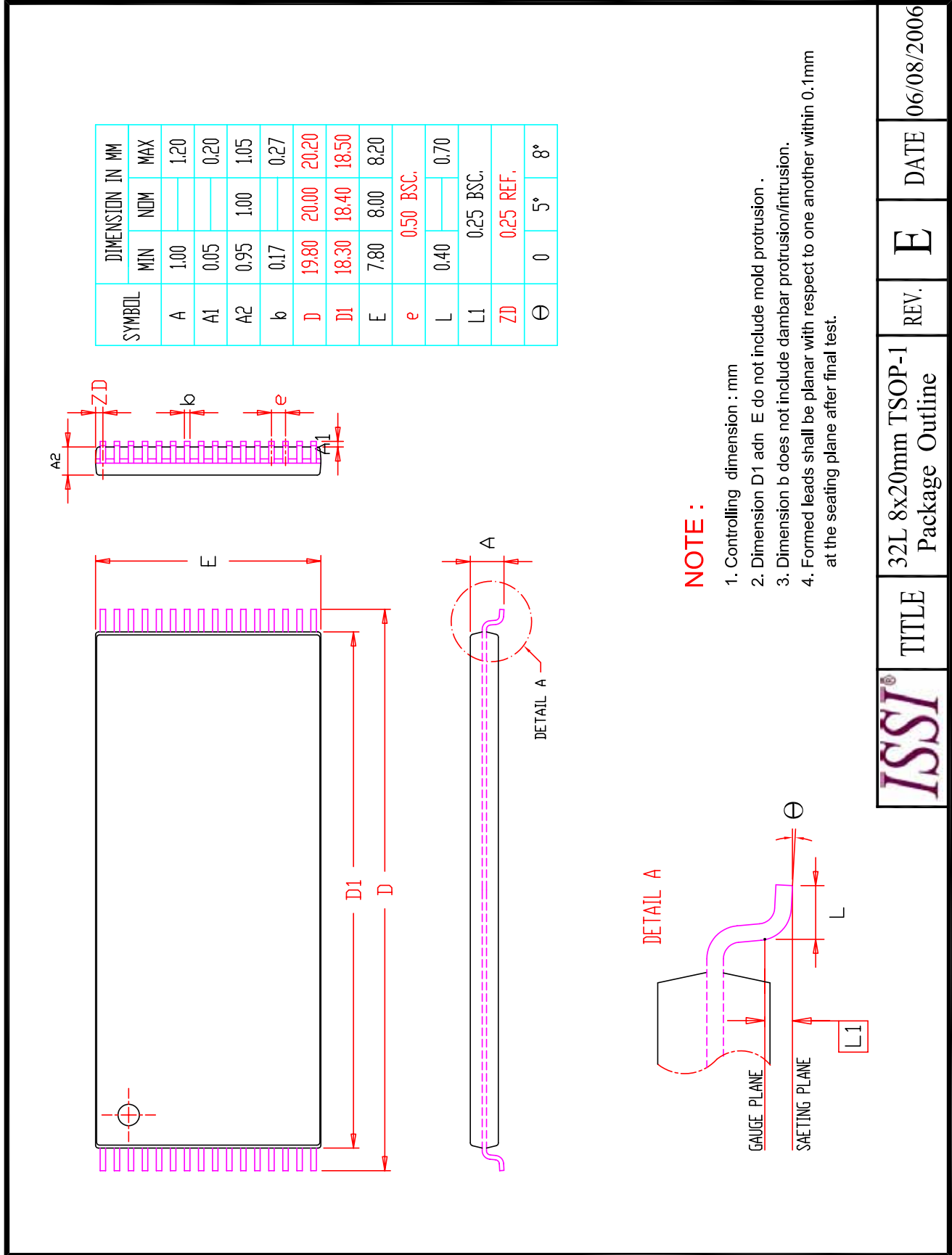
**NOTE :**

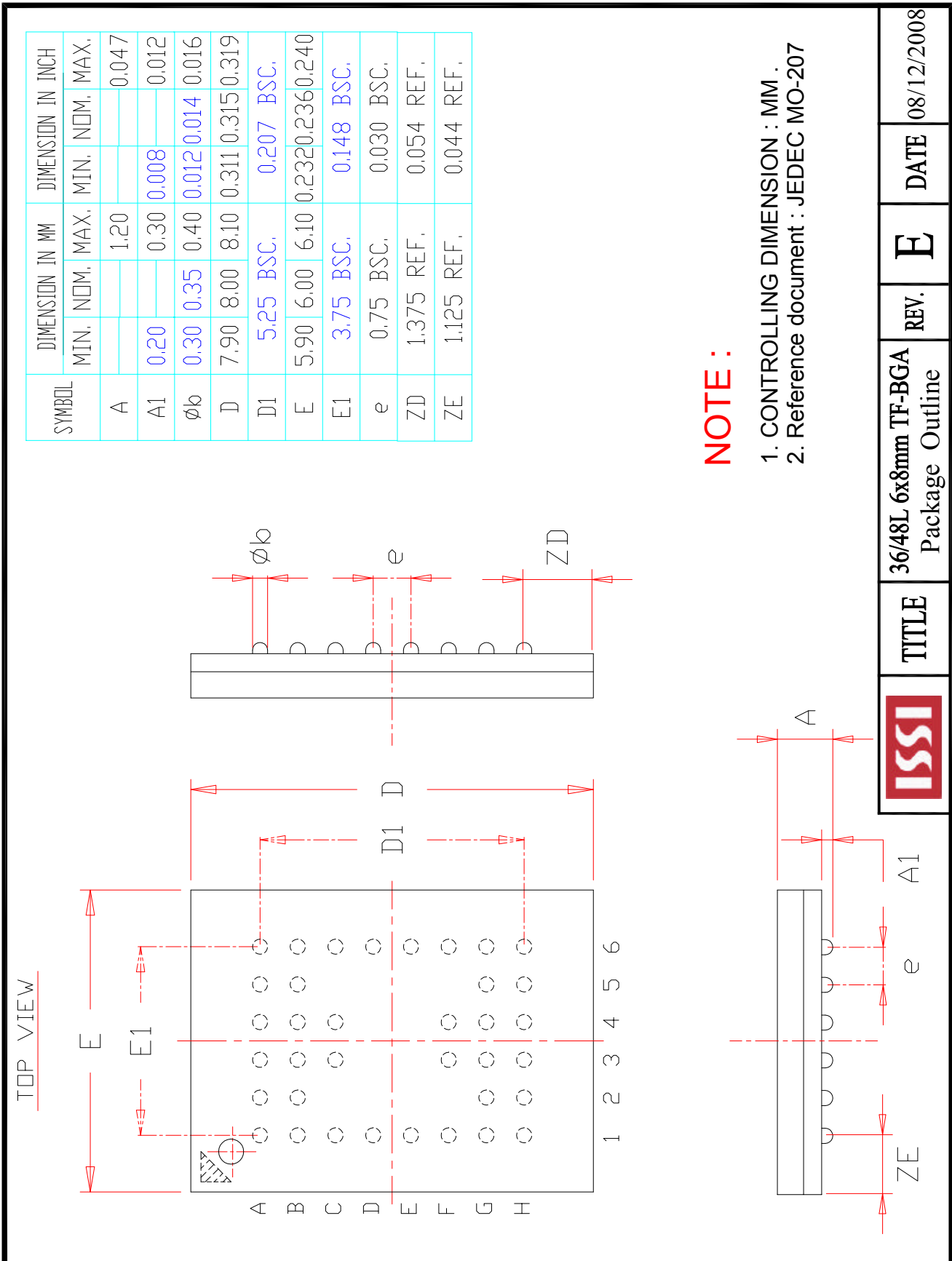
1. Controlling Dimension : mm
2. Dimension D1 and E do not include mold protrusion.
3. Dimension b does not include dambar protrusion/intrusion.
4. Reference Document : JEDEC MO-183
5. Formed leads shall be planar with respect to one another within 0.1mm at the seating plane after final test.



**CASE 2**

|   |                                     |      |            |
|---|-------------------------------------|------|------------|
|  | TITLE                               | REV. | DATE       |
|   | 32L 8x13.4mm TSOP-1 Package Outline | F    | 06/21/2017 |





| SYMBOL | DIMENSION IN MM |      |      | DIMENSION IN INCH |       |       |
|--------|-----------------|------|------|-------------------|-------|-------|
|        | MIN.            | NOM. | MAX. | MIN.              | NOM.  | MAX.  |
| A      |                 |      | 1.20 |                   |       | 0.047 |
| A1     | 0.20            |      | 0.30 | 0.008             |       | 0.012 |
| øb     | 0.30            | 0.35 | 0.40 | 0.012             | 0.014 | 0.016 |
| D      | 7.90            | 8.00 | 8.10 | 0.311             | 0.315 | 0.319 |
| D1     | 5.25 BSC.       |      |      | 0.207 BSC.        |       |       |
| E      | 5.90            | 6.00 | 6.10 | 0.232             | 0.236 | 0.240 |
| E1     | 3.75 BSC.       |      |      | 0.148 BSC.        |       |       |
| e      | 0.75 BSC.       |      |      | 0.030 BSC.        |       |       |
| ZD     | 1.375 REF.      |      |      | 0.054 REF.        |       |       |
| ZE     | 1.125 REF.      |      |      | 0.044 REF.        |       |       |

**NOTE :**

1. CONTROLLING DIMENSION : MM .
2. Reference document : JEDEC MO-207

|  |       |                                     |      |   |      |            |
|--|-------|-------------------------------------|------|---|------|------------|
|  | TITLE | 36/48L 6x8mm TF-BGA Package Outline | REV. | E | DATE | 08/12/2008 |
|--|-------|-------------------------------------|------|---|------|------------|